

Dated 4th November, 2017

Expression of Interest for resolution plan for Tecpro Systems Limited (TSL)

Tecpro Systems Limited (TSL), incorporated on November 7, 1990 is into designing, engineering, manufacturing, erection and commissioning of material handling and ash handling systems on turnkey basis for the core infrastructure related sectors like power, steel, cement and other industries. The Company also engages in EPC and BOP contracts for the power sector.

Corporate Insolvency resolution process was initiated in respect of Tecpro Systems Limited (“the Company” or “the Corporate Debtor”) under the provisions of the Insolvency and Bankruptcy Code, 2016 (“IBC”) by an order of National Company Law Tribunal (“NCLT”) (**Order no C.A. NO. (IB) 197 (PB)/2017**) with effect from August 7, 2017. The NCLT had appointed Mr. Venkatesan Sankaranarayanan (IP Registration no. IBBI/IPA-001/IP-P00123/20172018/10265) as the Interim Resolution Professional (“IRP”) for the Company with effect from August 7, 2017. His appointment as the Resolution Professional (“RP”) has been confirmed by the Committee of Creditors (“CoC”) constituted for the Company in the first CoC meeting held on September 13, 2017. Ernst & Young (EY) was appointed towards assistance in preparing the resolution plan and finalisation.

The RP under the provisions of Section 25(2)(h) of the IBC hereby invites all prospective lenders, investors, and any other persons (“Potential Resolution Applicant”) to submit their resolution plan for insolvency in respect of the Corporate Debtor.

Any Potential Resolution Applicant who is desirous of submitting a resolution plan as above will have to submit certified true copies of their Audited financial statements for last 3 years and any other information that may be relevant and sought by the RP. Also, they shall be required to execute a Non-Disclosure Agreement (“NDA”) as per the requirements of the IBC and the Insolvency and Bankruptcy Board of India (Insolvency Resolution Process for Corporate Persons) Regulations, 2016 (“CIRP Regulations”) as a condition for receiving the information memorandum (“IM”) and other relevant information in relation to the Corporate Debtor. Potential Resolution Applicants are requested to adhere to the timeline for executing the NDA, and receive the IM and any other information required on or before February 1, 2018.

Potential Resolution Applicants are encouraged to submit resolution plans in accordance with the provisions of the IBC and the regulations thereunder on or before February 15, 2018.

All further queries and submission in regards to the resolution plan must be sent via email addressed to venkat.ip17@gmail.com or by submitting physical / hard copies of the proposed resolution plan to Mr. Venkatesan Sankaranarayanan at the following address - Unit no.2, First floor, No.25, First Main Road, Gandhi Nagar, Adyar, Chennai-600020, Tamilnadu. India.

The consideration, evaluation and approval of eligible resolution plans forwarded by the RP to the CoC is within the powers of the CoC under the provisions of the IBC and the CIRP Regulations. The CoC may specify evaluation criteria for evaluation of the resolution plans.

Please note that the RP is bound by law to present to the CoC for its approval under the IBC, only such resolution plans which conform to the conditions set out under Section 30(2) of the IBC read along with Regulation 38 of the CIRP Regulations. All Potential Resolution Applicants who are desirous of submitting a Resolution Plan in respect of the Corporate Debtor must read, understand and comply with all requirements under the IBC, the CIRP Regulations and any other applicable law that are in force now or which may come into force subsequently, in relation to the resolution plan and all matters under, pursuant to, in furtherance of or in relation to, this invitation.

For clarifications, if any, please send mail to venkat.ip17@gmail.com.

**Venkatesan Sankaranarayanan,
Resolution Professional
Tecpro Systems Limited**

Note: The resolution professional appointed has the right to accept, reject or modify any application without assigning any reason or liability.